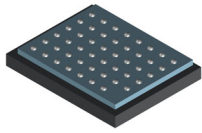
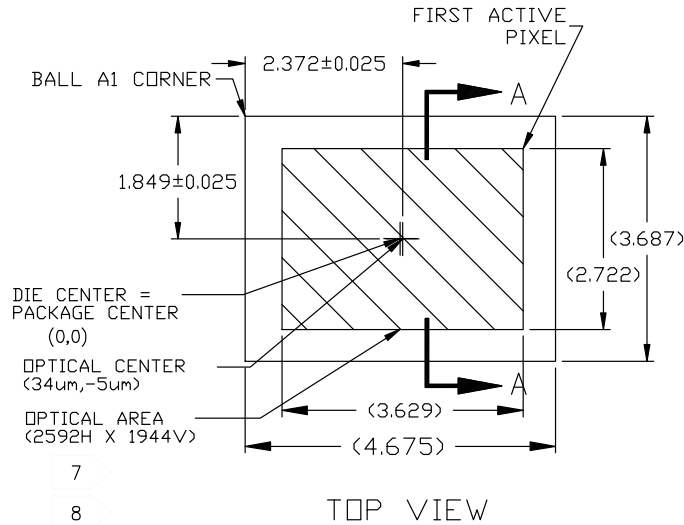


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



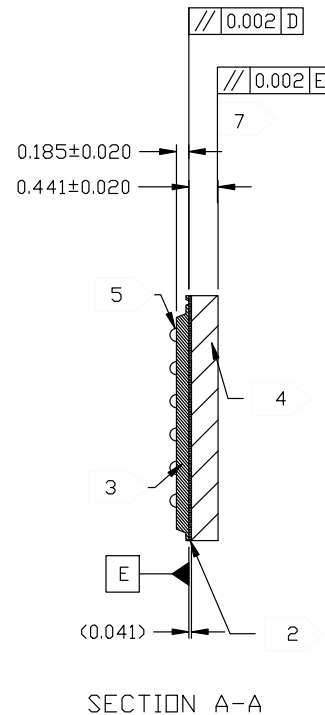
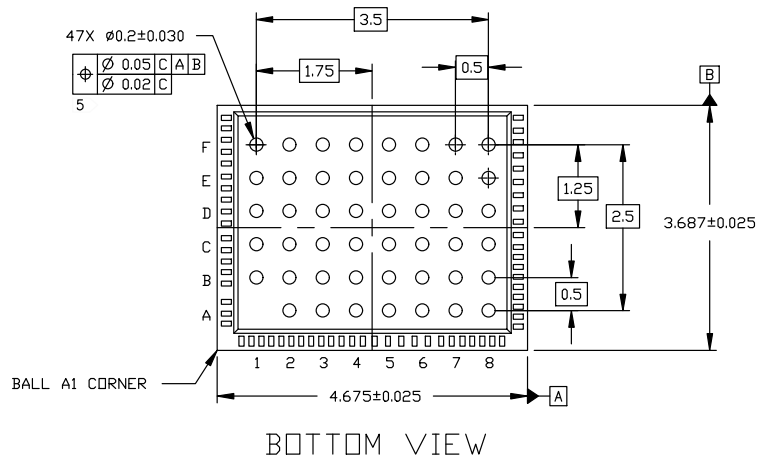
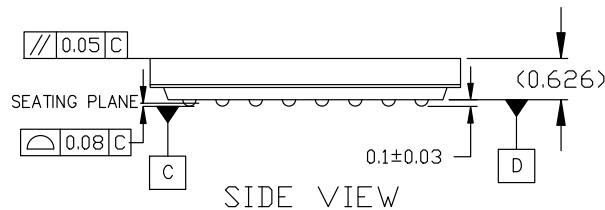
ODCSP47 4.675x3.687
CASE 570AW
ISSUE O

DATE 02 FEB 2023



NOTES:

1. DIMENSIONS IN MM. DIMENSIONS IN () ARE FOR REFERENCE ONLY.
2. ENCAPSULANT: EPOXY
3. SUBSTRATE MATERIAL: SILICON.
4. LID MATERIAL: BORSILICATED GLASS 0.4 THICKNESS.
5. SOLDER BALL MATERIAL: SAC305 (96.5% Sn, 3% Ag, 0.5% Cu)
6. SOLDER BALL PAD: $\phi 0.200$ SMD
7. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO PACKAGE EDGES: $\pm 0.1^\circ$.
MAXIMUM TILT OF OPTICAL AREA ARE RELATIVE TO SUBSTRATE PLANE D: 2UM.
MAXIMUM TILT OF COVER GLASS RELATIVE TO OPTICAL AREA PLANE E: 2UM
8. OPTICAL AREA IS DEFINES BY THE ACTIVE PIXEL ARRAY AND IS NOT DELINEATED BY THE LIGHT BLOCK BOUNDARY. REFER TO THE DEVICE DATA SHEET FOR TOTAL ARRAY AND FIRST PIXEL DEFINITIONS.



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DESCRIPTION:	ODCSP47 4.675x3.687	PAGE 1 OF 1

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